

T495C157K004ATE250

T495, Tantalum, MnO2 Tantalum, Commercial Grade, 150 uF, 10%, 4 VDC, SMD, MnO2, Molded, Low ESR, 250 mOhms, 6032, 2.8 mm, 1.3 mm

CATHODE (-) END VIEW



ANODE (+) END VIEW

Dimensions

L

W

н

т s

F

А

В

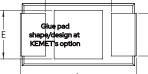
E G

Ρ

R

Х

SIDE VIEW



6mm +/-0.3mm

3.2mm +/-0.3mm 2.5mm +/-0.3mm

1.3mm +/-0.3mm

2.2mm +/-0.1mm

0.5mm +/-0.15mm

0.1mm +/-0.1mm REF

0.13mm REF

2.9mm MIN

2.4mm REF

2.8mm REF

0.9mm REF

1mm REF

Click here for the 3D model.

General Information	
Series	T495
Dielectric	MnO2 Tantalum
Style	SMD Chip
Description	SMD, MnO2, Molded, Low ESR
Features	Low ESR
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	224.48 mg
Shelf Life	156 Weeks
MSL	1

Capacitance150 uFTolerance10%Voltage DC4 VDC (85C), 2.68 VDC (125C)Temperature Range-55/+125°CRated Temperature85°CDissipation Factor8% 120Hz 25CFailure RateN/A	fications	
Voltage DC4 VDC (85C), 2.68 VDC (125C)Temperature Range-55/+125°CRated Temperature85°CDissipation Factor8% 120Hz 25C	itance	150 uF
Temperature Range-55/+125°CRated Temperature85°CDissipation Factor8% 120Hz 25C	nce	10%
Rated Temperature85°CDissipation Factor8% 120Hz 25C	je DC	4 VDC (85C), 2.68 VDC (125C)
Dissipation Factor 8% 120Hz 25C	erature Range	-55/+125°C
	Temperature	85°C
Failure Rate N/A	ation Factor	8% 120Hz 25C
	Rate	N/A
ESR 250 mOhms (100kHz 25C)		250 mOhms (100kHz 25C)
Ripple Current 663 mA (rms, 100kHz 25C), 596.7 mA (rms, 85C), 265.2 mA (rms, 125C)	Current	596.7 mÀ (rms, 85C), 265.2 mA
Leakage Current6 uA (5min 25°C)	ge Current	6 uA (5min 25°C)

Packaging Specifications	
Packaging	T&R, 178mm
Packaging Quantity	500

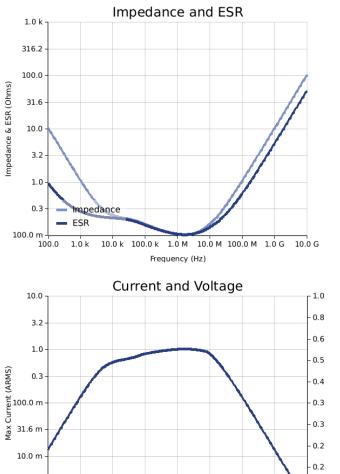
Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

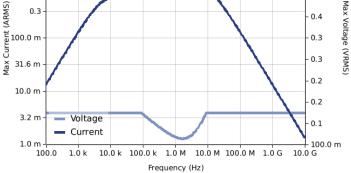


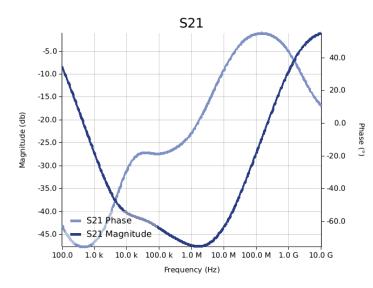
T495, Tantalum, MnO2 Tantalum, Commercial Grade, 150 uF, 10%, 4 VDC, SMD, MnO2, Molded, Low ESR, 250 mOhms, 6032, 2.8 mm, 1.3 mm

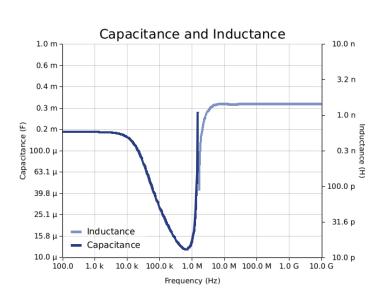
Simulations

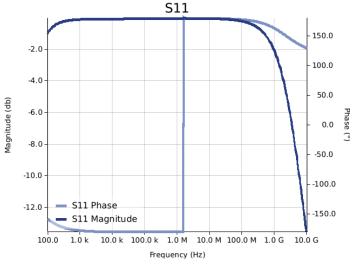
For the complete simulation environment please visit K-SIM.













T495, Tantalum, MnO2 Tantalum, Commercial Grade, 150 uF, 10%, 4 VDC, SMD, MnO2, Molded, Low ESR, 250 mOhms, 6032, 2.8 mm, 1.3 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics.
 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.